

## FR-4 Process capability

NO	Item	Craft Ability
1	Surface Finish	HASL, Immersion Gold, Gold Plating, OSP, Immersion Tin, etc
2	Layer	1-32 layers
3	Min. Line Width	4mil
4	Min. Line Space	4mil
5	Min. Space between Pad to Pad	3mil
6	Min. Hole Diameter	0.20mm
7	Min. Bonding Pad Diameter	0.2mm
8	Max. Proportion of Drilling Hole and Board Thickness	1:10:00
9	Max. Size of Finish Board	23inch*35inch
10	Rang of Finish Board' s Thickness	0.21-3.2mm
11	Min. Thickness of Soldermask	10um
12	Soldermask	Green, Yellow, Black, White, Red, transparent photosensitive solder mask, Strippable solder mask
13	Min. Linewidth of Idents	4mil
14	Min. Height of Idents	25mil
15	Color of Silk-screen	White, Yellow, Black
16	Date File Format	Gerber file and Drilling file, Report series, PADS 2000 series, powerpcb series, ODB++
17	E-testing	100%E-Test: High Voltage Testing
18	Material for PCB	High TG Material: High Frequency (ROGERS, TEFLON, TADONIC, ARLON): Halogen free Material
19	Other Test	Impedance Testing, Resisitance Testing, Microsection etc
20	Special Technological Requirement	Blind&Buried Vias and High Thickness Copper